


Common-mode Chokes

Material Data Sheet

Product Class:	SMD Common-mode chokes B82721S0xxxxxxx B78512AxxxxA003	
Date	22.07.2021	
IMDS ID if available		
Version:	03	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS** [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Manganese Zinc Ferrite	100	12645-49-7	38.0	
	Polymer	2C	Epoxy	100	25068-38-6	1.3	
	Heavy Metal	1C	Cu	100	7440-50-8	32.1	
	Elastomer	2B	Polyamide (PA)	100	24993-04-2	1.6	
Encapsulation and Mounting	Thermoplastic	2A	Phenolic	35-50	9003-35-4	19.2	
			Glass fiber	50-65	65997-17-3		
Termination	Heavy Metal	1C	Cu	100	7440-50-8	3	
	Heavy Metal	1C	Sn	100	7440-31-5	0.2	
Sum in total:						100.0	

Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers	Size W x L x H [max. in mm]	Weight [approx. in g]	Part Numbers
17.02X19.3X10.1	4.8	B82721S0272T040;P301297	17.02X19.3X10.1	4.7	B78512A8287A003***
17.02X19.3X10.1	4.3	B82721S0282A030;P301296	17.02X19.3X10.1	5.2	B78512A8213A003
17.02X19.3X10.1	4.6	B82721S0322A020;P301295	17.02X19.3X10.1	4.6	B78512A8286A003
17.02X19.3X10.1	5.2	B82721S0572A020; P301293	17.02X19.3X10.1	4.3	B78512A7896A003
17.02X19.3X10.1	4.7	B82721S0322A010;P301292 ***	17.02X19.3X10.1	4.8	B78512A9713A003
17.02X19.3X10.1	4.9	B82721S0562A030;P301294	17.02X19.3X10.1	5.2	B78512A7856A003
17.02X19.3X10.1	5.2	B82721S0572A040;P301652			

Not part of a Product Class

Contact	Dr. Johann Reindl, MAG EPQM	Important remarks: 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.
Division	TDK Electronics AG, Magnetics Business Group (MAG)	
Address	Rosenheimer Strasse 116b, 81669 Munich	
	Tel: +49 89 54020 3030 mailto: johann.reindl@tdk-electronics.tdk.com	
*) others: (not declarable or prohibited substances acc. GADSL) **) typical mass percentage of substance ***) core is Nickel-Zink-Ferrite CAS 12645-50-0		

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (valid not valid)

no exemptions;

- Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;
- Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound;
- Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- Other Exemption than above